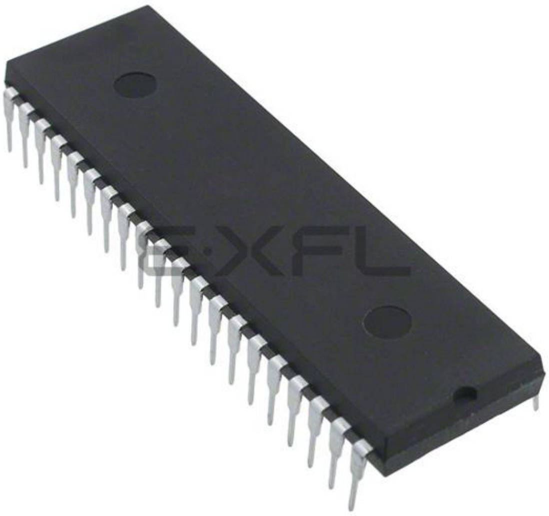

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	40/20MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	32
Program Memory Size	64KB (64K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIL
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ts87c51rd2-mia

Mnemonic	Pin Number			Type	Name And Function
ALE/$\overline{\text{PROG}}$	30	33	27	O (I)	**Address Latch Enable/Program Pulse:** Output pulse for latching the low byte of the address during an access to external memory. In normal operation, ALE is emitted at a constant rate of 1/6 (1/3 in X2 mode) the oscillator frequency, and can be used for external timing or clocking. Note that one ALE pulse is skipped during each access to external data memory. This pin is also the program pulse input ($\overline{\text{PROG}}$) during EPROM programming. ALE can be disabled by setting SFR's AUXR.0 bit. With this bit set, ALE will be inactive during internal fetches.
$\overline{\text{PSEN}}$	29	32	26	O	**Program Store ENable:** The read strobe to external program memory. When executing code from the external program memory, $\overline{\text{PSEN}}$ is activated twice each machine cycle, except that two $\overline{\text{PSEN}}$ activations are skipped during each access to external data memory. $\overline{\text{PSEN}}$ is not activated during fetches from internal program memory.
$\overline{\text{EA}}$/V_{PP}	31	35	29	I	**External Access Enable/Programming Supply Voltage:** $\overline{\text{EA}}$ must be externally held low to enable the device to fetch code from external program memory locations 0000H and 3FFFH (RB) or 7FFFH (RC), or FFFFH (RD). If EA is held high, the device executes from internal program memory unless the program counter contains an address greater than 3FFFH (RB) or 7FFFH (RC) $\overline{\text{EA}}$ must be held low for ROMless devices. This pin also receives the 12.75V programming supply voltage (V_{PP}) during EPROM programming. If security level 1 is programmed, $\overline{\text{EA}}$ will be internally latched on Reset.
XTAL1	19	21	15	I	**Crystal 1:** Input to the inverting oscillator amplifier and input to the internal clock generator circuits.
XTAL2	18	20	14	O	**Crystal 2:** Output from the inverting oscillator amplifier

ASSEMBLY LANGUAGE

```
; Block move using dual data pointers
; Destroys DPTR0, DPTR1, A and PSW
; note: DPS exits opposite of entry state
; unless an extra INC AUXR1 is added
;
00A2                AUXR1 EQU 0A2H
;
0000  909000       MOV  DPTR,#SOURCE          ; address of SOURCE
0003  05A2         INC   AUXR1                ; switch data pointers
0005  90A000       MOV  DPTR,#DEST            ; address of DEST
0008               LOOP:
0008  05A2         INC   AUXR1                ; switch data pointers
000A  E0           MOVX A,@DPTR               ; get a byte from SOURCE
000B  A3           INC   DPTR                 ; increment SOURCE address
000C  05A2         INC   AUXR1                ; switch data pointers
000E  F0           MOVX @DPTR,A               ; write the byte to DEST
000F  A3           INC   DPTR                 ; increment DEST address
0010  70F6         JNZ   LOOP                 ; check for 0 terminator
0012  05A2         INC   AUXR1                ; (optional) restore DPS
```

INC is a short (2 bytes) and fast (12 clocks) way to manipulate the DPS bit in the AUXR1 SFR. However, note that the INC instruction does not directly force the DPS bit to a particular state, but simply toggles it. In simple routines, such as the block move example, only the fact that DPS is toggled in the proper sequence matters, not its actual value. In other words, the block move routine works the same whether DPS is '0' or '1' on entry. Observe that without the last instruction (INC AUXR1), the routine will exit with DPS in the opposite state.

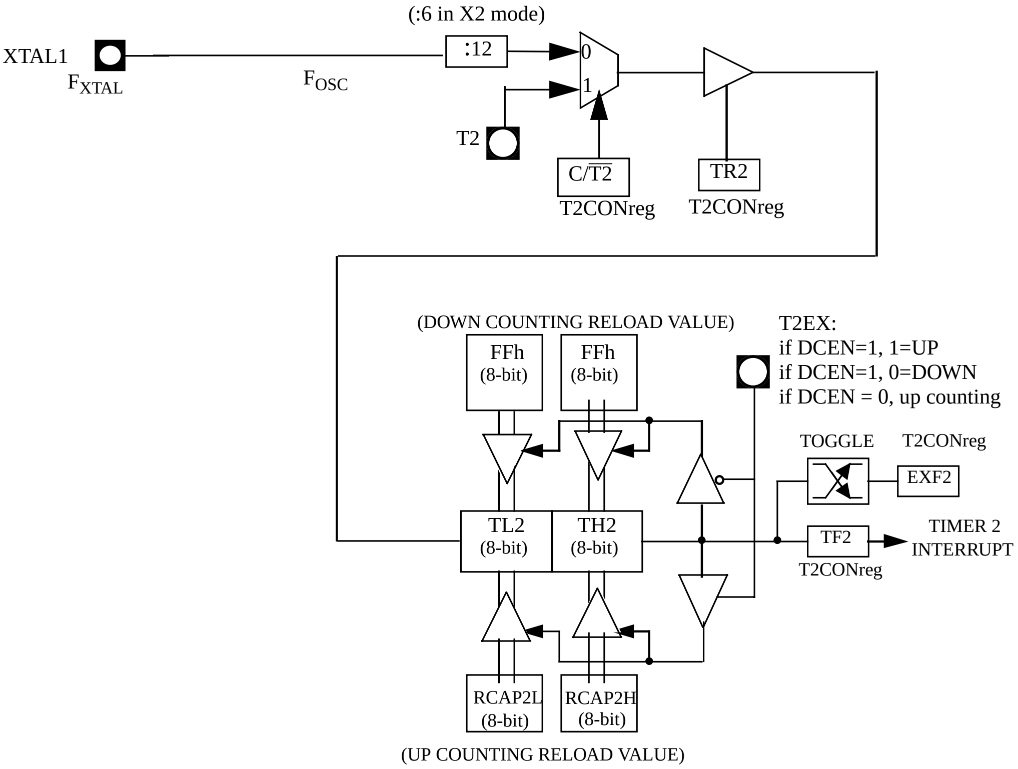


Figure 5. Auto-Reload Mode Up/Down Counter (DCEN = 1)

6.4.2. Programmable Clock-Output

In the clock-out mode, timer 2 operates as a 50%-duty-cycle, programmable clock generator (See Figure 6) . The input clock increments TL2 at frequency $F_{OSC}/2$. The timer repeatedly counts to overflow from a loaded value. At overflow, the contents of RCAP2H and RCAP2L registers are loaded into TH2 and TL2. In this mode, timer 2 overflows do not generate interrupts. The formula gives the clock-out frequency as a function of the system oscillator frequency and the value in the RCAP2H and RCAP2L registers :

$$Clock-OutFrequency = \frac{F_{osc}}{4 \times (65536 - RCAP2H/RCAP2L)}$$

For a 16 MHz system clock, timer 2 has a programmable frequency range of 61 Hz ($F_{OSC}/2^{16}$) to 4 MHz ($F_{OSC}/4$). The generated clock signal is brought out to T2 pin (P1.0).

Timer 2 is programmed for the clock-out mode as follows:

- Set T2OE bit in T2MOD register.
- Clear C/$\overline{T2}$ bit in T2CON register.
- Determine the 16-bit reload value from the formula and enter it in RCAP2H/RCAP2L registers.
- Enter a 16-bit initial value in timer registers TH2/TL2. It can be the same as the reload value or a different one depending on the application.
- To start the timer, set TR2 run control bit in T2CON register.

It is possible to use timer 2 as a baud rate generator and a clock generator simultaneously. For this configuration, the baud rates and clock frequencies are not independent since both functions use the values in the RCAP2H and RCAP2L registers.

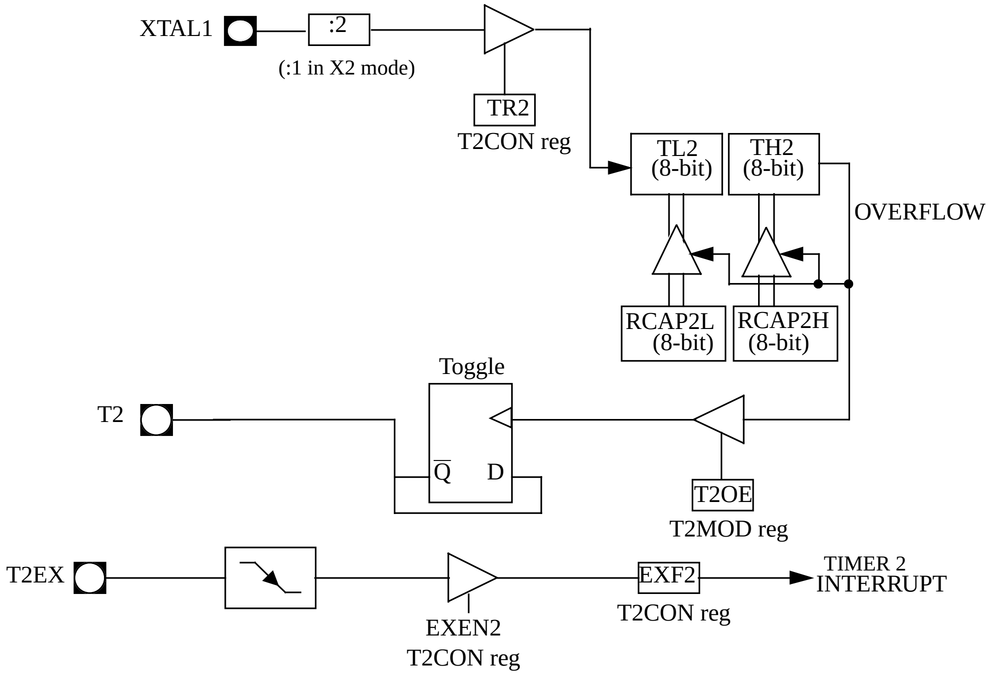


Figure 6. Clock-Out Mode C/$\overline{T2}$ = 0

- The ECF bit which when set causes an interrupt and the PCA overflow flag CF (in the CCON SFR) to be set when the PCA timer overflows.

The CCON SFR contains the run control bit for the PCA and the flags for the PCA timer (CF) and each module (Refer to Table 9).

- Bit CR (CCON.6) must be set by software to run the PCA. The PCA is shut off by clearing this bit.
- Bit CF: The CF bit (CCON.7) is set when the PCA counter overflows and an interrupt will be generated if the ECF bit in the CMOD register is set. The CF bit can only be cleared by software.
- Bits 0 through 4 are the flags for the modules (bit 0 for module 0, bit 1 for module 1, etc.) and are set by hardware when either a match or a capture occurs. These flags also can only be cleared by software.

Table 9. CCON: PCA Counter Control Register

CCON Address 0D8H	CF	CR	-	CCF4	CCF3	CCF2	CCF1	CCF0
Reset value	0	0	X	0	0	0	0	0

Symbol	Function
CF	PCA Counter Overflow flag. Set by hardware when the counter rolls over. CF flags an interrupt if bit ECF in CMOD is set. CF may be set by either hardware or software but can only be cleared by software.
CR	PCA Counter Run control bit. Set by software to turn the PCA counter on. Must be cleared by software to turn the PCA counter off.
-	Not implemented, reserved for future use.[a]
CCF4	PCA Module 4 interrupt flag. Set by hardware when a match or capture occurs. Must be cleared by software.
CCF3	PCA Module 3 interrupt flag. Set by hardware when a match or capture occurs. Must be cleared by software.
CCF2	PCA Module 2 interrupt flag. Set by hardware when a match or capture occurs. Must be cleared by software.
CCF1	PCA Module 1 interrupt flag. Set by hardware when a match or capture occurs. Must be cleared by software.
CCF0	PCA Module 0 interrupt flag. Set by hardware when a match or capture occurs. Must be cleared by software.

[a] User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.

The watchdog timer function is implemented in module 4 (See Figure 10).

The PCA interrupt system is shown in Figure 8

Table 12. CCAPnH: PCA Modules Capture/Compare Registers High

CCAPnH Address n = 0 - 4	**CCAP0H=0FAH CCAP1H=0FBH CCAP2H=0FCH CCAP3H=0FDH CCAP4H=0FEH**								
		7	**6**	**5**	**4**	**3**	**2**	**1**	**0**
	Reset value	0	0	0	0	0	0	0	0

Table 13. CCAPnL: PCA Modules Capture/Compare Registers Low

CCAPnL Address n = 0 - 4	**CCAP0L=0EAH CCAP1L=0EBH CCAP2L=0ECH CCAP3L=0EDH CCAP4L=0EEH**								
		7	**6**	**5**	**4**	**3**	**2**	**1**	**0**
	Reset value	0	0	0	0	0	0	0	0

Table 14. CH: PCA Counter High

CH Address 0F9H									
		7	**6**	**5**	**4**	**3**	**2**	**1**	**0**
	Reset value	0	0	0	0	0	0	0	0

Table 15. CL: PCA Counter Low

CL Address 0E9H									
		7	**6**	**5**	**4**	**3**	**2**	**1**	**0**
	Reset value	0	0	0	0	0	0	0	0

6.5.2. 16-bit Software Timer / Compare Mode

The PCA modules can be used as software timers by setting both the ECOM and MAT bits in the modules CCAPMn register. The PCA timer will be compared to the module's capture registers and when a match occurs an interrupt will occur if the CCFn (CCON SFR) and the ECCFn (CCAPMn SFR) bits for the module are both set (See Figure 10).

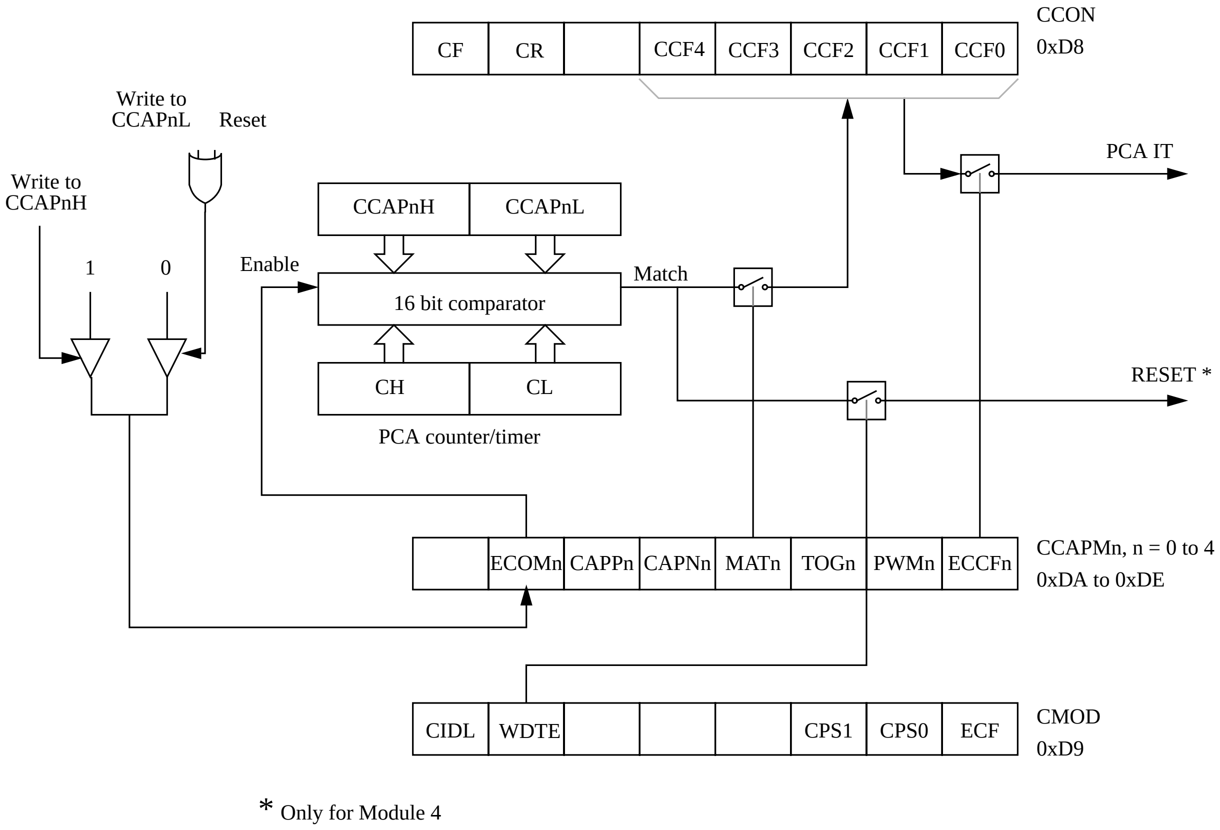


Figure 10. PCA Compare Mode and PCA Watchdog Timer

Before enabling ECOM bit, CCAPnL and CCAPnH should be set with a non zero value, otherwise an unwanted match could happen. Writing to CCAPnH will set the ECOM bit.

Once ECOM set, writing CCAPnL will clear ECOM so that an unwanted match doesn't occur while modifying the compare value. Writing to CCAPnH will set ECOM. For this reason, user software should write CCAPnL first, and then CCAPnH. Of course, the ECOM bit can still be controlled by accessing to CCAPMn register.

Table 17. PCON Register

PCON - Power Control Register (87h)

7	6	5	4	3	2	1	0
SMOD1	**SMOD0**	**-**	**POF**	**GF1**	**GF0**	**PD**	**IDL**

Bit Number	Bit Mnemonic	Description
7	SMOD1	**Serial port Mode bit 1** Set to select double baud rate in mode 1, 2 or 3.
6	SMOD0	**Serial port Mode bit 0** Clear to select SM0 bit in SCON register. Set to to select FE bit in SCON register.
5	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
4	POF	**Power-Off Flag** Clear to recognize next reset type. Set by hardware when VCC rises from 0 to its nominal voltage. Can also be set by software.
3	GF1	**General purpose Flag** Cleared by user for general purpose usage. Set by user for general purpose usage.
2	GF0	**General purpose Flag** Cleared by user for general purpose usage. Set by user for general purpose usage.
1	PD	**Power-Down mode bit** Cleared by hardware when reset occurs. Set to enter power-down mode.
0	IDL	**Idle mode bit** Clear by hardware when interrupt or reset occurs. Set to enter idle mode.

Reset Value = 00X1 0000b
Not bit addressable

Power-off flag reset value will be 1 only after a power on (cold reset). A warm reset doesn’t affect the value of this bit.

6.7. Interrupt System

The TS80C51Rx2 has a total of 7 interrupt vectors: two external interrupts ($\overline{\text{INT0}}$ and $\overline{\text{INT1}}$), three timer interrupts (timers 0, 1 and 2), the serial port interrupt and the PCA global interrupt. These interrupts are shown in Figure 16.

WARNING: Note that in the first version of RC devices, the PCA interrupt is in the lowest priority. Thus the order in $\overline{\text{INT0}}$, TF0, $\overline{\text{INT1}}$, TF1, RI or TI, TF2 or EXF2, PCA.

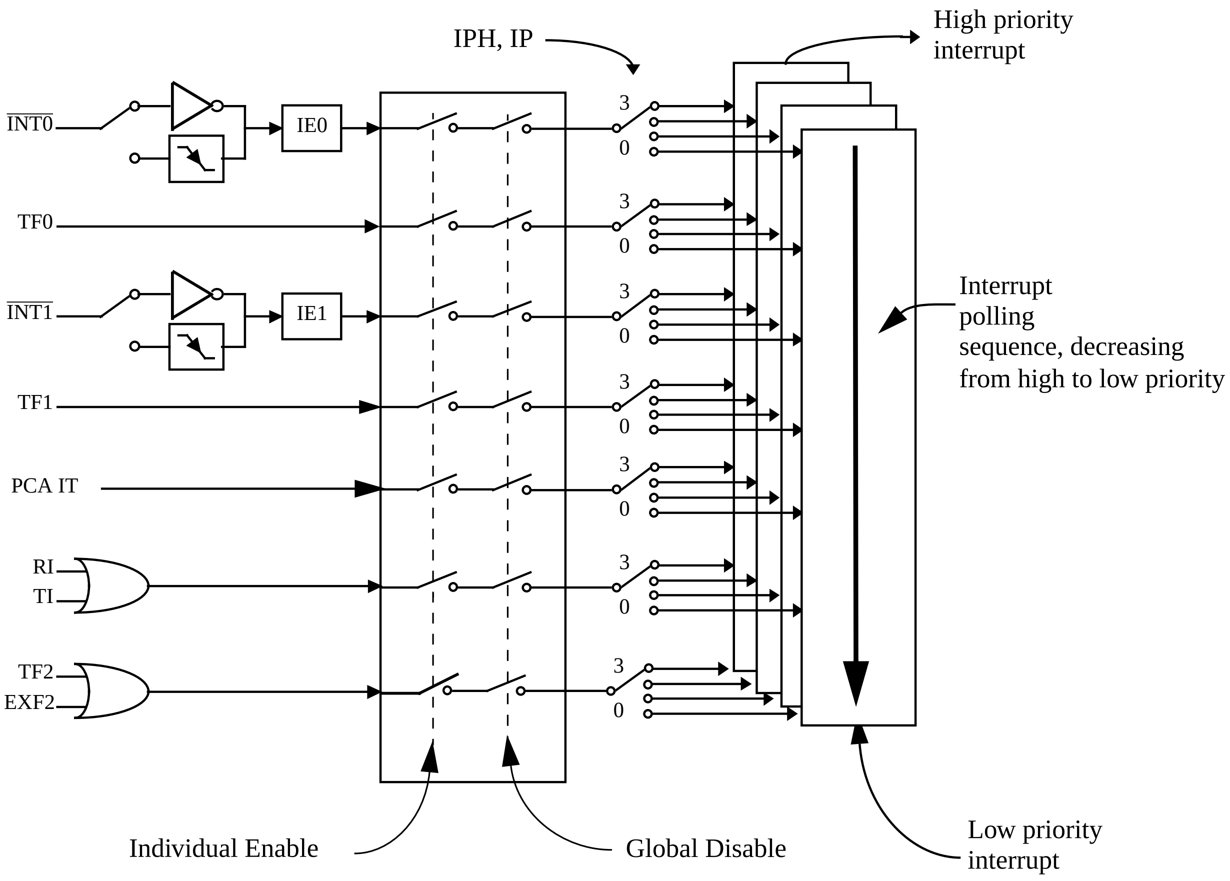


Figure 16. Interrupt Control System

Each of the interrupt sources can be individually enabled or disabled by setting or clearing a bit in the Interrupt Enable register (See Table 19.). This register also contains a global disable bit, which must be cleared to disable all interrupts at once.

Each interrupt source can also be individually programmed to one out of four priority levels by setting or clearing a bit in the Interrupt Priority register (See Table 20.) and in the Interrupt Priority High register (See Table 21.). shows the bit values and priority levels associated with each combination.

The PCA interrupt vector is located at address 0033H. All other vector addresses are the same as standard C52 devices.

6.8. Idle mode

An instruction that sets PCON.0 causes that to be the last instruction executed before going into the Idle mode. In the Idle mode, the internal clock signal is gated off to the CPU, but not to the interrupt, Timer, and Serial Port functions. The CPU status is preserved in its entirely : the Stack Pointer, Program Counter, Program Status Word, Accumulator and all other registers maintain their data during Idle. The port pins hold the logical states they had at the time Idle was activated. ALE and PSEN hold at logic high levels.

There are two ways to terminate the Idle. Activation of any enabled interrupt will cause PCON.0 to be cleared by hardware, terminating the Idle mode. The interrupt will be serviced, and following RETI the next instruction to be executed will be the one following the instruction that put the device into idle.

The flag bits GF0 and GF1 can be used to give an indication if an interrupt occured during normal operation or during an Idle. For example, an instruction that activates Idle can also set one or both flag bits. When Idle is terminated by an interrupt, the interrupt service routine can examine the flag bits.

The other way of terminating the Idle mode is with a hardware reset. Since the clock oscillator is still running, the hardware reset needs to be held active for only two machine cycles (24 oscillator periods) to complete the reset.

6.9. Power-Down Mode

To save maximum power, a power-down mode can be invoked by software (Refer to Table 17., PCON register).

In power-down mode, the oscillator is stopped and the instruction that invoked power-down mode is the last instruction executed. The internal RAM and SFRs retain their value until the power-down mode is terminated. V_{CC} can be lowered to save further power. Either a hardware reset or an external interrupt can cause an exit from power-down. To properly terminate power-down, the reset or external interrupt should not be executed before V_{CC} is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize.

Only external interrupts $\overline{\text{INT0}}$ and $\overline{\text{INT1}}$ are useful to exit from power-down. For that, interrupt must be enabled and configured as level or edge sensitive interrupt input.
Holding the pin low restarts the oscillator but bringing the pin high completes the exit as detailed in Figure 17. When both interrupts are enabled, the oscillator restarts as soon as one of the two inputs is held low and power down exit will be completed when the first input will be released. In this case the higher priority interrupt service routine is executed.
Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put TS80C51Rx2 into power-down mode.

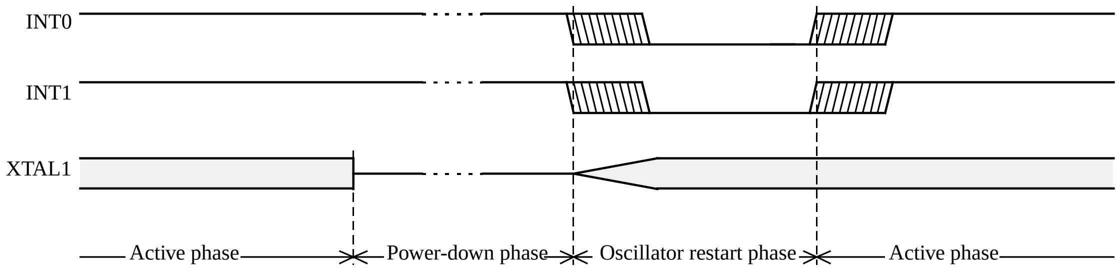


Figure 17. Power-Down Exit Waveform

Exit from power-down by reset redefines all the SFRs, exit from power-down by external interrupt does no affect the SFRs.

Exit from power-down by either reset or external interrupt does not affect the internal RAM content.

NOTE: If idle mode is activated with power-down mode (IDL and PD bits set), the exit sequence is unchanged, when execution is vectored to interrupt, PD and IDL bits are cleared and idle mode is not entered.

6.12. Power-Off Flag

The power-off flag allows the user to distinguish between a “cold start” reset and a “warm start” reset.

A cold start reset is the one induced by V_{CC} switch-on. A warm start reset occurs while V_{CC} is still applied to the device and could be generated for example by an exit from power-down.

The power-off flag (POF) is located in PCON register (See Table 26.). POF is set by hardware when V_{CC} rises from 0 to its nominal voltage. The POF can be set or cleared by software allowing the user to determine the type of reset.

The POF value is only relevant with a Vcc range from 4.5V to 5.5V. For lower Vcc value, reading POF bit will return indeterminate value.

Table 26. PCON Register

PCON - Power Control Register (87h)

7	6	5	4	3	2	1	0
SMOD1	**SMOD0**	**-**	**POF**	**GF1**	**GF0**	**PD**	**IDL**

Bit Number	Bit Mnemonic	Description
7	SMOD1	**Serial port Mode bit 1** Set to select double baud rate in mode 1, 2 or 3.
6	SMOD0	**Serial port Mode bit 0** Clear to select SM0 bit in SCON register. Set to to select FE bit in SCON register.
5	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
4	POF	**Power-Off Flag** Clear to recognize next reset type. Set by hardware when V_{CC} rises from 0 to its nominal voltage. Can also be set by software.
3	GF1	**General purpose Flag** Cleared by user for general purpose usage. Set by user for general purpose usage.
2	GF0	**General purpose Flag** Cleared by user for general purpose usage. Set by user for general purpose usage.
1	PD	**Power-Down mode bit** Cleared by hardware when reset occurs. Set to enter power-down mode.
0	IDL	**Idle mode bit** Clear by hardware when interrupt or reset occurs. Set to enter idle mode.

Reset Value = 00X1 0000b
Not bit addressable

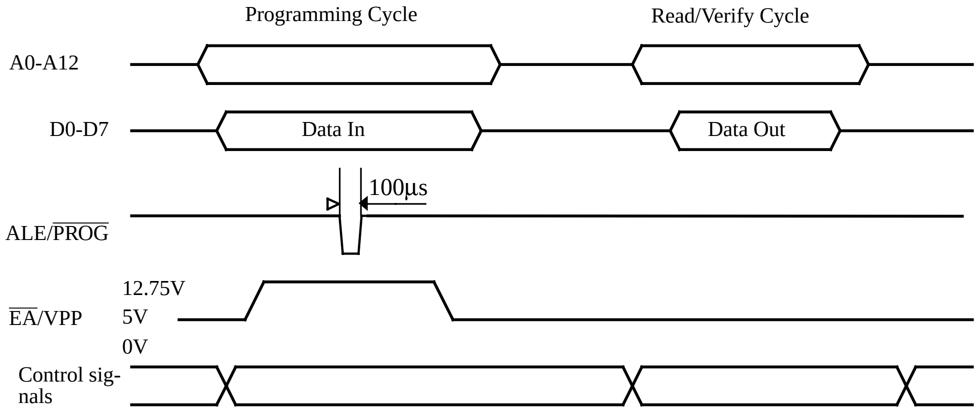


Figure 19. Programming and Verification Signal’s Waveform

8.4. EPROM Erasure (Windowed Packages Only)

Erasing the EPROM erases the code array, the encryption array and the lock bits returning the parts to full functionality.

Erasure leaves all the EPROM cells in a 1’s state (FF).

8.4.1. Erasure Characteristics

The recommended erasure procedure is exposure to ultraviolet light (at 2537 Å) to an integrated dose at least 15 W-sec/cm^2. Exposing the EPROM to an ultraviolet lamp of 12,000 µW/cm^2 rating for 30 minutes, at a distance of about 25 mm, should be sufficient. An exposure of 1 hour is recommended with most of standard erasers.

Erasure of the EPROM begins to occur when the chip is exposed to light with wavelength shorter than approximately 4,000 Å. Since sunlight and fluorescent lighting have wavelengths in this range, exposure to these light sources over an extended time (about 1 week in sunlight, or 3 years in room-level fluorescent lighting) could cause inadvertent erasure. If an application subjects the device to this type of exposure, it is suggested that an opaque label be placed over the window.

10. Electrical Characteristics

10.1. Absolute Maximum Ratings (1)

Ambiant Temperature Under Bias:	
C = commercial	0°C to 70°C
I = industrial	-40°C to 85°C
Storage Temperature	-65°C to + 150°C
Voltage on V_{CC} to V_{SS}	-0.5 V to + 7 V
Voltage on V_{PP} to V_{SS}	-0.5 V to + 13 V
Voltage on Any Pin to V_{SS}	-0.5 V to V_{CC} + 0.5 V
Power Dissipation	1 W(2)

NOTES

1. Stresses at or above those listed under " Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

2. This value is based on the maximum allowable die temperature and the thermal resistance of the package.

10.2. Power consumption measurement

Since the introduction of the first C51 devices, every manufacturer made operating Icc measurements under reset, which made sense for the designs were the CPU was running under reset. In Atmel Wireless & Microcontrollers new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That's why, while keeping measurements under Reset, Atmel Wireless & Microcontrollers presents a new way to measure the operating Icc:

Using an internal test ROM, the following code is executed:

```
Label:    SJMP Label (80 FE)
```

Ports 1, 2, 3 are disconnected, Port 0 is tied to FFh, EA = Vcc, RST = Vss, XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating Icc.

10.3. DC Parameters for Standard Voltage

TA = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 5 V ± 10%; F = 0 to 40 MHz.
TA = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 5 V ± 10%; F = 0 to 40 MHz.

Table 32. DC Parameters in Standard Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		0.2 V_{CC} - 0.1	V	
V_{IH}	Input High Voltage except XTAL1, RST	0.2 V_{CC} + 0.9		V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage, XTAL1, RST	0.7 V_{CC}		V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3, 4, 5(6)			0.3 0.45 1.0	V V V	I_{OL} = 100 µA(4) I_{OL} = 1.6 mA(4) I_{OL} = 3.5 mA(4)
V_{OL1}	Output Low Voltage, port 0 (6)			0.3 0.45 1.0	V V V	I_{OL} = 200 µA(4) I_{OL} = 3.2 mA(4) I_{OL} = 7.0 mA(4)
V_{OL2}	Output Low Voltage, ALE, $\overline{PSEN}$			0.3 0.45 1.0	V V V	I_{OL} = 100 µA(4) I_{OL} = 1.6 mA(4) I_{OL} = 3.5 mA(4)
V_{OH}	Output High Voltage, ports 1, 2, 3, 4, 5	V_{CC} - 0.3 V_{CC} - 0.7 V_{CC} - 1.5			V V V	I_{OH} = -10 µA I_{OH} = -30 µA I_{OH} = -60 µA V_{CC} = 5 V ± 10%
V_{OH1}	Output High Voltage, port 0	V_{CC} - 0.3 V_{CC} - 0.7 V_{CC} - 1.5			V V V	I_{OH} = -200 µA I_{OH} = -3.2 mA I_{OH} = -7.0 mA V_{CC} = 5 V ± 10%
V_{OH2}	Output High Voltage,ALE, $\overline{PSEN}$	V_{CC} - 0.3 V_{CC} - 0.7 V_{CC} - 1.5			V V V	I_{OH} = -100 µA I_{OH} = -1.6 mA I_{OH} = -3.5 mA V_{CC} = 5 V ± 10%
R_{RST}	RST Pulldown Resistor	50	90 (5)	200	kΩ	
I_{IL}	Logical 0 Input Current ports 1, 2, 3, 4, 5			-50	µA	Vin = 0.45 V
I_{LI}	Input Leakage Current			±10	µA	0.45 V < Vin < V_{CC}
I_{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3, 4, 5			-650	µA	Vin = 2.0 V
C_{IO}	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz TA = 25°C
I_{PD}	Power Down Current		20 (5)	50	µA	2.0 V < V_{CC} < 5.5 V(3)
I_{CC} under RESET	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.4 Freq (MHz) @12MHz 5.8 @16MHz 7.4	mA	V_{CC} = 5.5 V(1)

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
I_{CC} operating	Power Supply Current Maximum values, X1 mode: (7)			3 + 0.6 Freq (MHz) @12MHz 10.2 @16MHz 12.6	mA	V_{CC} = 5.5 V(8)
I_{CC} idle	Power Supply Current Maximum values, X1 mode: (7)			0.25+0.3Freq (MHz) @12MHz 3.9 @16MHz 5.1	mA	V_{CC} = 5.5 V(2)

10.4. DC Parameters for Low Voltage

TA = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5 V ± 10%; F = 0 to 30 MHz.
TA = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5 V ± 10%; F = 0 to 30 MHz.

Table 33. DC Parameters for Low Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		0.2 V_{CC} - 0.1	V	
V_{IH}	Input High Voltage except XTAL1, RST	0.2 V_{CC} + 0.9		V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage, XTAL1, RST	0.7 V_{CC}		V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3, 4, 5 (6)			0.45	V	I_{OL} = 0.8 mA(4)
V_{OL1}	Output Low Voltage, port 0, ALE, $\overline{PSEN}$ (6)			0.45	V	I_{OL} = 1.6 mA(4)
V_{OH}	Output High Voltage, ports 1, 2, 3, 4, 5	0.9 V_{CC}			V	I_{OH} = -10 µA
V_{OH1}	Output High Voltage, port 0, ALE, $\overline{PSEN}$	0.9 V_{CC}			V	I_{OH} = -40 µA
I_{IL}	Logical 0 Input Current ports 1, 2, 3, 4, 5			-50	µA	Vin = 0.45 V
I_{LI}	Input Leakage Current			±10	µA	0.45 V < Vin < V_{CC}
I_{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3, 4, 5			-650	µA	Vin = 2.0 V
R_{RST}	RST Pulldown Resistor	50	90 (5)	200	kΩ	
CIO	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz TA = 25°C
I_{PD}	Power Down Current		20 (5) 10 (5)	50 30	µA	V_{CC} = 2.0 V to 5.5 V(3) V_{CC} = 2.0 V to 3.3 V(3)
I_{CC} under RESET	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.2 Freq (MHz) @12MHz 3.4 @16MHz 4.2	mA	V_{CC} = 3.3 V(1)
I_{CC} operating	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.3 Freq (MHz) @12MHz 4.6 @16MHz 5.8	mA	V_{CC} = 3.3 V(8)

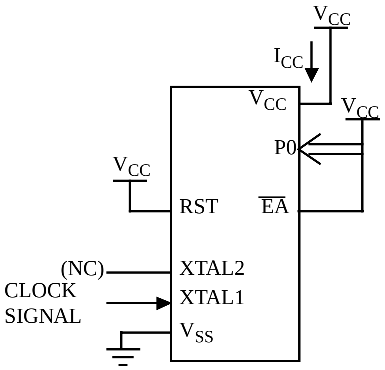
Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
I_{CC} idle	Power Supply Current Maximum values, X1 mode: $^{(7)}$			0.15 Freq (MHz) + 0.2 @12MHz 2 @16MHz 2.6	mA	V_{CC} = 3.3 $V^{(2)}$

NOTES

1. *I_{CC} under reset is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns (see Figure 24.), $V_{IL} = V_{SS} + 0.5$ V, $V_{IH} = V_{CC} - 0.5$V; XTAL2 N.C.; $\overline{EA}$ = RST = Port 0 = V_{CC}. I_{CC} would be slightly higher if a crystal oscillator used..*
2. *Idle I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns, $V_{IL} = V_{SS} + 0.5$ V, $V_{IH} = V_{CC} - 0.5$ V; XTAL2 N.C; Port 0 = V_{CC}; $\overline{EA}$ = RST = V_{SS} (see Figure 22.).*
3. *Power Down I_{CC} is measured with all output pins disconnected; $\overline{EA}$ = V_{SS}, PORT 0 = V_{CC}; XTAL2 NC.; RST = V_{SS} (see Figure 23.).*
4. *Capacitance loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OL}s of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1 to 0 transitions during bus operation. In the worst cases (capacitive loading 100pF), the noise pulse on the ALE line may exceed 0.45V with maxi V_{OL} peak 0.6V. A Schmitt Trigger use is not necessary.*
5. *Typicals are based on a limited number of samples and are not guaranteed. The values listed are at room temperature and 5V.*
6. *Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:*
   Maximum I_{OL} per port pin: 10 mA
   Maximum I_{OL} per 8-bit port:
   Port 0: 26 mA
   Ports 1, 2, 3 and 4 and 5 when available: 15 mA
   Maximum total I_{OL} for all output pins: 71 mA

If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.

7. *For other values, please contact your sales office.*
8. *Operating I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns (see Figure 24.), $V_{IL} = V_{SS} + 0.5$ V, $V_{IH} = V_{CC} - 0.5$V; XTAL2 N.C.; $\overline{EA}$ = Port 0 = V_{CC}; RST = V_{SS}. The internal ROM runs the code 80 FE (label: SJMP label). I_{CC} would be slightly higher if a crystal oscillator is used. Measurements are made with OTP products when possible, which is the worst case.*



All other pins are disconnected.

Figure 20. I_{CC} Test Condition, under reset

Table 40. AC Parameters for a Fix Clock

Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	
T_{RLRH}	130		85		135		125		175		ns
T_{WLWH}	130		85		135		125		175		ns
T_{RLDV}		100		60		102		95		137	ns
T_{RHDX}	0		0		0		0		0		ns
T_{RHDZ}		30		18		35		25		42	ns
T_{LLDV}		160		98		165		155		222	ns
T_{AVDV}		165		100		175		160		235	ns
T_{LLWL}	50	100	30	70	55	95	45	105	70	130	ns
T_{AVWL}	75		47		80		70		103		ns
T_{QVWX}	10		7		15		5		13		ns
T_{QVWH}	160		107		165		155		213		ns
T_{WHQX}	15		9		17		10		18		ns
T_{RLAZ}		0		0		0		0		0	ns
T_{WHLH}	10	40	7	27	15	35	5	45	13	53	ns

For timing purposes a port pin is no longer floating when a 100 mV change from load voltage occurs and begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs. $I_{OL}/I_{OH} \geq \pm$ 20mA.

10.5.15. Clock Waveforms

Valid in normal clock mode. In X2 mode XTAL2 signal must be changed to XTAL2 divided by two.

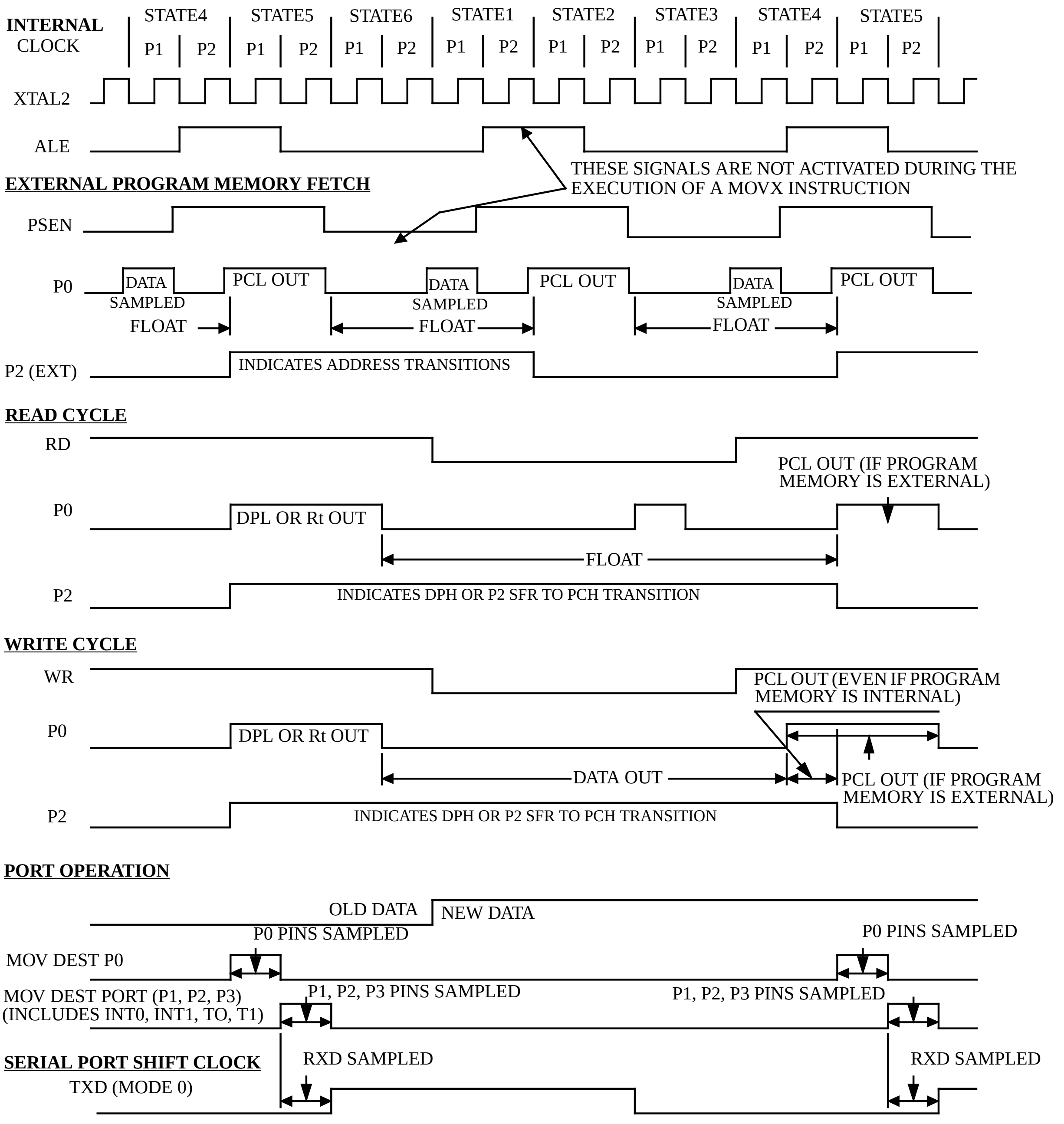


Figure 33. Clock Waveforms

This diagram indicates when signals are clocked internally. The time it takes the signals to propagate to the pins, however, ranges from 25 to 125 ns. This propagation delay is dependent on variables such as temperature and pin loading. Propagation also varies from output to output and component. Typically though (T_A=25°C fully loaded) $\overline{RD}$ and $\overline{WR}$ propagation delays are approximately 50ns. The other signals are typically 85 ns. Propagation delays are incorporated in the AC specifications.

Table 48. Possible Ordering Entries

	TS80C51RA2/RD2 ROMless	TS83C51RB2/RC2/RD2zzz ROM	TS87C51RB2/RC2/RD2 OTP
-MCA	X	X	X
-MCB	X	X	X
-MCE	X	X	X
-MCL	RD2 only	RD2 only	RD2 only
-MCM	RD2 only	RD2 only	RD2 only
-VCA	X	X	X
-VCB	X	X	X
-VCE	X	X	X
-VCL	RD2 only	RD2 only	RD2 only
-VCM	RD2 only	RD2 only	RD2 only
-LCA	X	X	X
-LCB	X	X	X
-LCE	X	X	X
-LCL	RD2 only	RD2 only	RD2 only
-LCM	RD2 only	RD2 only	RD2 only
-MIA	X	X	X
-MIB	X	X	X
-MIE	X	X	X
-MIL	RD2 only	RD2 only	RD2 only
-MIM	RD2 only	RD2 only	RD2 only
-VIA	X	X	X
-VIB	X	X	X
-VIE	X	X	X
-VIL	RD2 only	RD2 only	RD2 only
-VIM	RD2 only	RD2 only	RD2 only
-LIA	X	X	X
-LIB	X	X	X
-LIE	X	X	X
-LIL	RD2 only	RD2 only	RD2 only
-LIM	RD2 only	RD2 only	RD2 only
-EA	X		X
-EB	X		X
-EE	X		X
-EL	RD2 only		RD2 only
-EM	RD2 only		RD2 only
-EJ			RC2 and RD2 only
-EK			RC2 and RD2 only
-EN			RD2 only

- -Ex for samples
- Tape and Reel available for B, E, L and M packages
- Dry pack mandatory for E and M packages